HY12P62
Datasheet
2000 Counts DMM Specialized IC
Embedded Digital T-RMS

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1. Features

- Operation voltage: 2.5V~3.6V
- 4K Word OTP (One Time Programmable) program memory, 256Byte data memory
- Built-in Brownout and Watch dog timer, preventing CPU from crash
- Built-in high precision RC oscillator
  - Operation mode: 4MHz
  - Idle mode: 32KHz
- Programmable multi-functional network
  - Voltage/resistor switch measurement
  - Constant voltage output
  - Positive/negative electrode differential
- Multi-functional comparator
  - Equipped with delay and latch function, reducing glitch
  - Programmable comparison voltage configuration
  - Short circuit test
- High resolution ΣΔADC
  - Zero input/output voltage
  - High input impedance (built-in input buffer)
  - Built-in absolute temperature sensor
- 1.2V internal analog circuit common-ground voltage source
- LVD low voltage detect function equips with 14-step voltage detect configuration and external input voltage detect function
- 4x12 LCD driver
  - Built-in charge pump regulated circuit, providing 4 LCD bias voltage
  - Static, 1/2, 1/3, 1/4 Duty and 1/3 Bias software selection
- 8-bit Timer A
- 8-bit Timer C module can generate PWM waveform
- Build-In EPROM (BIE)
- Support 6 stack level

Function List

Model No.	VDD	Internal Clock (Hz)	System Clock (Hz)	Program Memory / Data Memory / Built-in EPROM	ADC ENOB (bit)	Sample Rate (sps)	TPS / RTC / Serial Interface	PA Network / PB Channel / T-RMS Bandwidth (Hz)	I/O	LCD (com x seg) / Timer (bit x ch) / PWM (bit x ch)	Package
HY12P62	2.5V~3.6V	32K~4M	32K~8M	4K	19-bit	10~12.5k	Y	7	13	4 x 12	LQFP64
				256			Y	3		8-bit x 2	
				64			-	350		8-bit x 1	

2. Block Diagram

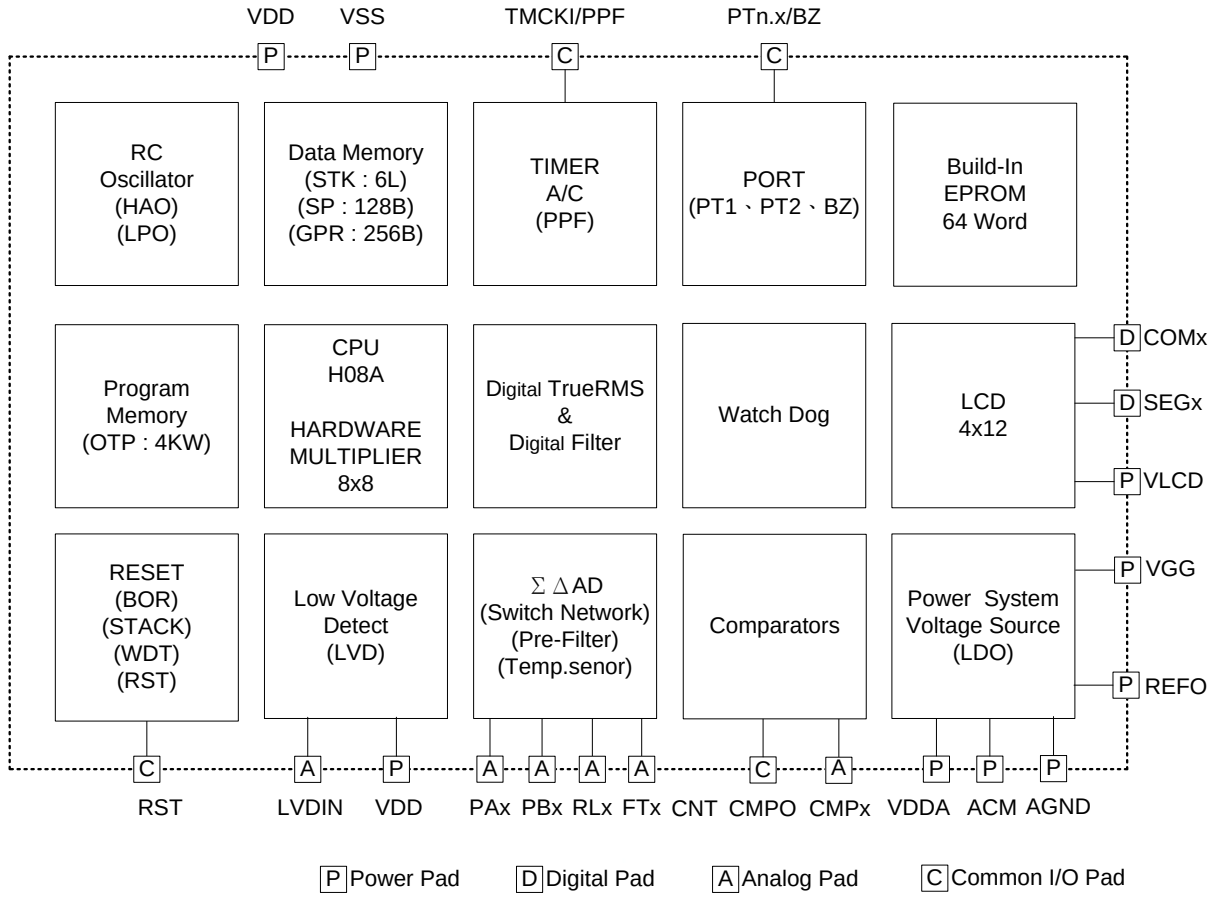
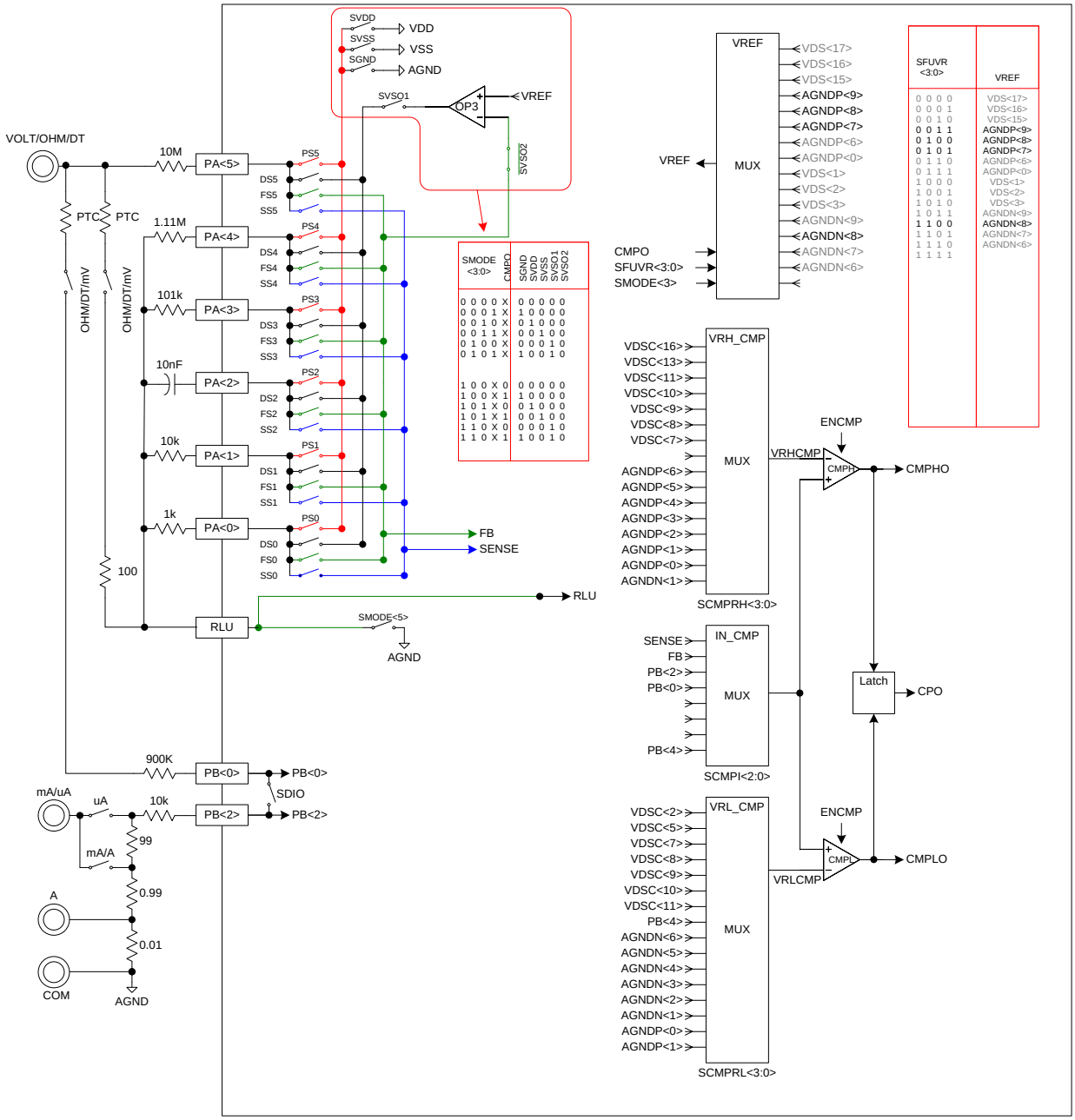


Figure 2-1 HY12P62 Register List

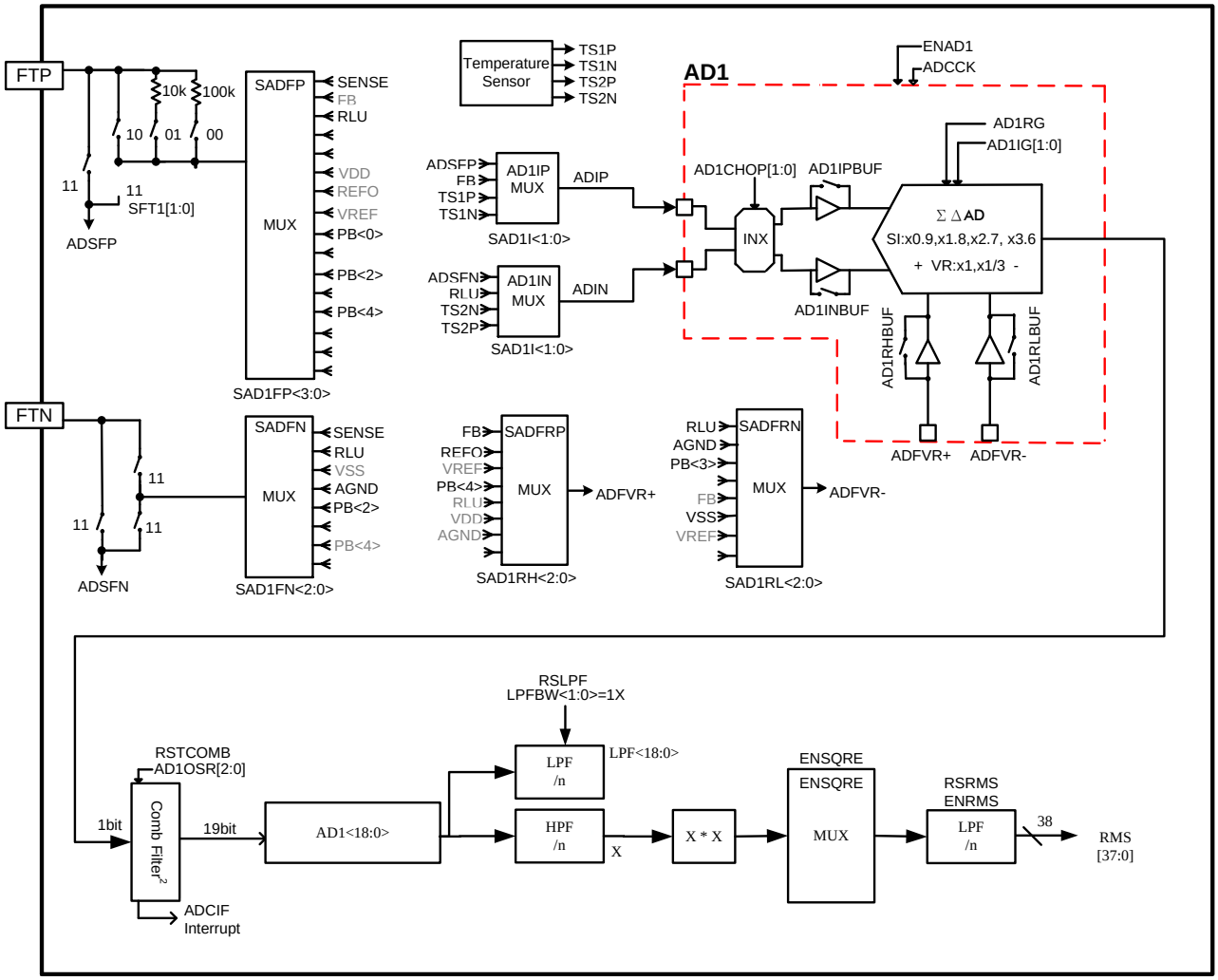
2.1 Multi-Function Block



Note:

The function of light gray characters in the block diagram is temporarily reserved, please do not use.

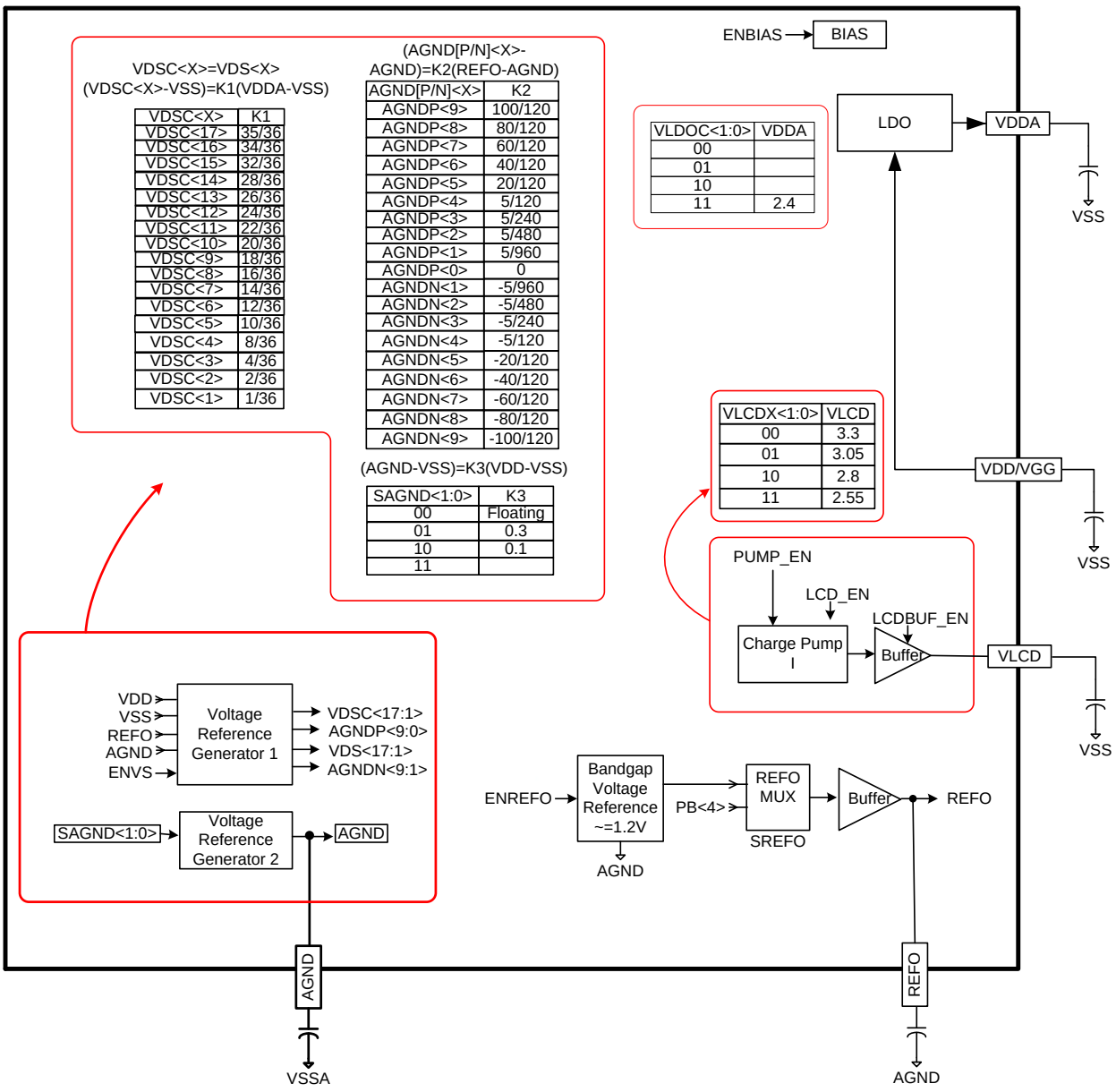
2.2 ADC



Note:

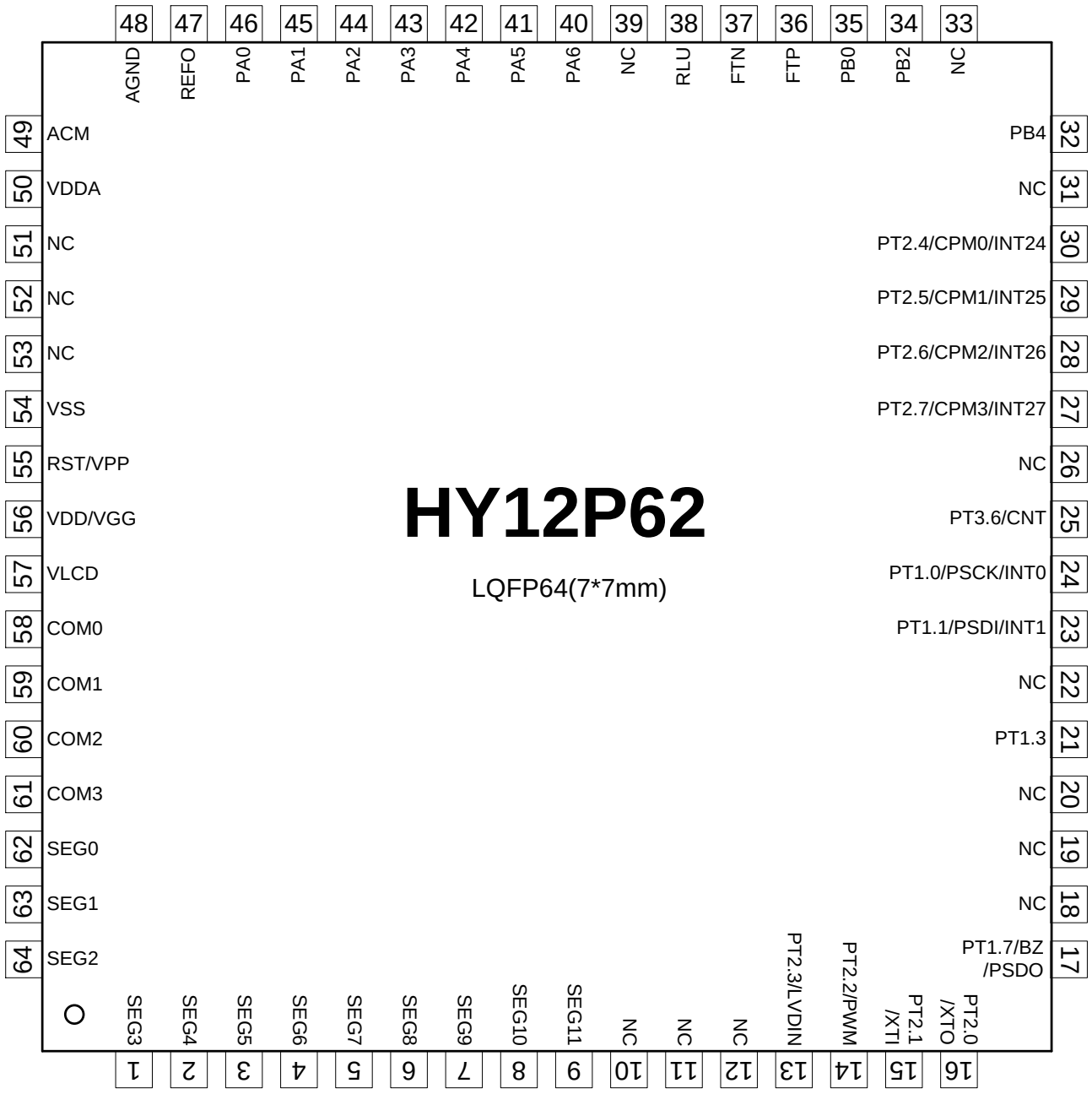
The function of light gray characters in the block diagram is temporarily reserved and is not open for use.

2.3 Power



3. Package And Pin

3.1. 64 PIN Diagram LQFP64



3.2. Pin Description

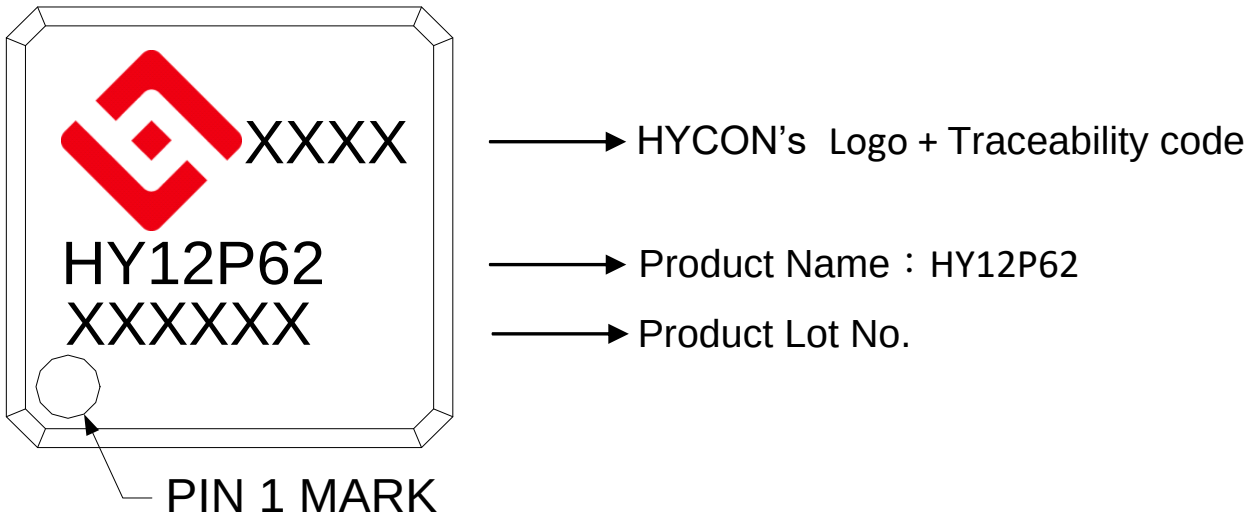
"I/O" Input/Output, "I" Input, "O" Output, "S" Schmitt Trigger, "C" CMOS, "P" Power, "A" Analog

Pin		Characteristic		Description
No.	Name	I/O	Type	
1	SEG3	O	A	Segment output of LCD
2	SEG4	O	A	Segment output of LCD
3	SEG5	O	A	Segment output of LCD
4	SEG6	O	A	Segment output of LCD
5	SEG7	O	A	Segment output of LCD
6	SEG8	O	A	Segment output of LCD
7	SEG9	O	A	Segment output of LCD
8	SEG10	O	A	Segment output of LCD
9	SEG11	O	A	Segment output of LCD
10	NC			No Connect
11	NC			No Connect
12	NC			No Connect
13	PT2.3/LVDIN PT2.3 LVDIN	 I/O I	 S A	 Digital input/output LVD external signal input port
14	PT2.2/PWM PT2.2 PWM	 I/O O	 C C	 Digital input/output PWM output port
15	PT2.1/XTI PT2.1 XTI	 I/O I	 S A	 Digital input/output Input port of external oscillator
16	PT2.0/XTO PT2.0 XTO	 I/O O	 S A	 Digital input/output Output port of external oscillator
17	PT1.7/BZ/PSDO PT1.7 BZ PSDO	 I/O O O	 S C C	 Digital input/output Buzzer output port PSDO port of OTP read/write interface
18	NC			No Connect
19	NC			No Connect
20	NC			No Connect
21	PT1.3	I	S	Digital input
22	NC			No Connect
23	PT1.1/PSDI/INT1			

	PT1.1	I/O	S	Digital input
	PSDI	I	S	PSDI of OTP read/write interface
	INT1	I	S	Interrupt source, INT1
24	PT1.0/PSCK/INT0			
	PT1.0	I/O	S	Digital input
	PSCK	I	S	PSCK of OTP read/write interface
	INT0	I	S	Interrupt source, INT0
25	PT3.6/CNT			
	PT3.6	I/O	S	Digital input/output
	CNT	I	S	Input port of frequency counter
26	NC			No Connect
27	PT2.7/CMP3/INT27			
	PT2.7	I/O	C	Digital input/output
	CMP3	I	A	Input port of comparator
	INT27	I	C	Interrupt source, E27IF
28	PT2.6/CMP2/INT26			
	PT2.6	I/O	S	Digital input/output
	CMP2	I	A	Input port of comparator
	INT26	I	S	Interrupt source, E26IF
29	PT2.5/CMP1/INT25			
	PT2.5	I/O	S	Digital input/output
	CMP1	I	A	Input port of comparator
	INT25	I	S	Interrupt source, E25IF
30	PT2.4/CMP0/INT24			
	PT2.4	I/O	S	Digital input/output
	CMP0	I	A	Input port of comparator
	INT24	I	S	Interrupt source, E24IF
31	NC			No Connect
32	PB4	I	A	Analog input channel
33	NC			No Connect
34	PB2	I	A	Analog input channel
35	PB0	I	A	Analog input channel
36	FTP	I/O	A	Capacitor connect port of pre-filter
37	FTN	I/O	A	Capacitor connect port of pre-filter
38	RLU	I/O	A	Switch of analog network
39	NC			No Connect
40	PA6	I/O	A	Switch of analog network
41	PA5	I/O	A	Switch of analog network

42	PA4	I/O	A	Switch of analog network
43	PA3	I/O	A	Switch of analog network
44	PA2	I/O	A	Switch of analog network
45	PA1	I/O	A	Switch of analog network
46	PA0	I/O	A	Switch of analog network
47	REFO	I/O	P	Voltage reference port
48	AGND	I/O	P	Analog power ground end
49	ACM	I/O	P	Voltage reference port
50	VDDA	I/O	P	Analog circuit voltage source
51	NC			No Connect
52	NC			No Connect
53	NC			No Connect
54	VSS	P	P	Ground end of IC operation voltage source
55	RST/VPP			
	RST	I	S	Reset IC (Low active)
	VPP	P	P	EPROM read/write voltage source
56	VDD/ VGG			
	VDD	P	P	Voltage source of IC operation
	VGG	P	P	Low Dropout Regulator Input
57	VLCD	I/O	P	Voltage source of LCD
58	COM0	O	A	COM output of LCD
59	COM1	O	A	COM output of LCD
60	COM2	O	A	COM output of LCD
61	COM3	O	A	COM output of LCD
62	SEG0	O	A	Segment output of LCD
63	SEG1	O	A	Segment output of LCD
64	SEG2	O	A	Segment output of LCD

3.2.1. LQFP package marker information



4. Register list

"-"no use,"*"read/write,"w"write,"r"read,"r0"only read 0,"r1"only read 1,"w0"only write 0,"w1"omly write 1												
"."unimplemented bit,"x"unknown,"u"unchanged,"d"depends on condition												
Address	**File Name**	**Bit7**	**Bit6**	**Bit5**	**Bit4**	**Bit3**	**Bit2**	**Bit1**	**Bit0**	**A-RESET**	**i-RESET**	**R/W**
00H	INDF0	Contents of FSR0 to address data memoryvalue of FSR0 not changed								N/A	N/A	*,*,*,*,*,*,*,*
01H	POINC0	Contents of FSR0 to address data memoryvalue of FSR0 post-incremented								N/A	N/A	*,*,*,*,*,*,*,*
02H	PODEC0	Contents of FSR0 to address data memoryvalue of FSR0 post-decremented								N/A	N/A	*,*,*,*,*,*,*,*
03H	PRINC0	Contents of FSR0 to address data memoryvalue of FSR0 pre-incremented								N/A	N/A	*,*,*,*,*,*,*,*
04H	PLUSW0	Contents of FSR0 to address data memoryvalue of FSR0 offset by W								N/A	N/A	*,*,*,*,*,*,*,*
05H	INDF1	Contents of FSR1 to address data memoryvalue of FSR0 not changed								N/A	N/A	*,*,*,*,*,*,*,*
06H	POINC1	Contents of FSR1 to address data memoryvalue of FSR0 post-incremented								N/A	N/A	*,*,*,*,*,*,*,*
07H	PODEC1	Contents of FSR1 to address data memoryvalue of FSR0 post-decremented								N/A	N/A	*,*,*,*,*,*,*,*
08H	PRINC1	Contents of FSR1 to address data memoryvalue of FSR0 pre-incremented								N/A	N/A	*,*,*,*,*,*,*,*
09H	PLUSW1	Contents of FSR1 to address data memoryvalue of FSR0 offset by W								N/A	N/A	*,*,*,*,*,*,*,*
0FH	FSR0H								FSR0[8]	x	....u	-,-,-,- -,-,-,*
10H	FSR0L	Indirect Data Memory Address Pointer 0 Low Byte,FSR0[7:0]								xxxx xxxx	uuuu uuuu	*,*,*,*,*,*,*,*
11H	FSR1H								FSR1[8]	x	....u	-,-,-,- -,-,-,*
12H	FSR1L	Indirect Data Memory Address Pointer 1 Low Byte,FSR1[7:0]								xxxx xxxx	uuuu uuuu	*,*,*,*,*,*,*,*
16H	TOSH				Top-of-Stack High Byte (TOS<12:8>)					...0 0000	...0 0000	-,-,*,*,*,*,*,*
17H	TOSL	Top-of-Stack Low Byte (TOS<7:0>)								0000 0000	0000 0000	*,*,*,*,*,*,*,*
18H	STKPTR	STKFL	STKUN	STKOV			STKPRT[2]	STKPRT[1]	STKPRT[0]	000. .000	000. .000	r,rw0,rw0,- -,r,r,r
1AH	PCLATH				PC High Byte for PC<12:8>					...0 0000	...0 0000	-,-,*,*,*,*,*,*
1BH	PCLATL	PC Low Byte for PC<7:0>								0000 0000	0000 0000	*,*,*,*,*,*,*,*
1DH	TBLPTRH			Program Memory Table Pointer High Byte (TBLPTR<13:8>)						...0 0000	...0 0000	-,-,*,*,*,*,*,*
1EH	TBLPTRL	Program Memory Table Pointer Low Byte (TBLPTR<7:0>)								0000 0000	0000 0000	*,*,*,*,*,*,*,*
1FH	TBLDH	Program Memory Table Latch High Byte								0000 0000	0000 0000	*,*,*,*,*,*,*,*
20H	TBLDL	Program Memory Table Latch Low Byte								0000 0000	0000 0000	*,*,*,*,*,*,*,*
21H	PRODH	Product Register of Multiply High Byte								xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r
22H	PRODL	Product Register of Multiply Low Byte								xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r
23H	INTE1	GIE		TMCIE		TMAIE	WDTIE	E1IE	E0IE	0.0. 0000	0.0. 0000	*,-,*,- *,*,*,*
24H	INTE2			RMSIE	LPFIE	AD1IE		CTIE		0000 000.	0000 000.	*,*,*,*,*,*,*,-
25H	INTE3	E24IE	E25IE	E26IE	E27IE					0000	0000	*,*,*,*-,-,-,-,-
26H	INTF1			TMCIF		TMAIF	WDTIF	E1IF	E0IF	..0. 0000	..0. 0000	-,-,*,-*,*,*,*
27H	INTF2			RMSIF	LPFIF	AD1IF		CTIF		0000 000.	0000 000.	*,*,*,*,*,*,*,-
28H	INTF3	E24IF	E25IF	E26IF	E27IF					0000	0000	*,*,*,*-,-,-,-,-
29H	WREG	Working Register								xxxx xxxx	uuuu uuuu	*,*,*,*,*,*,*,*
2AH	BSRCN								BSR[0]	 0000	 0000	-,-,-,-,*,*,*,*
2BH	STATUS				C	DC	N	OV	Z	...x xxxx	...u uuuu	-,-,-,-*,*,*,*,*
2CH	PSTATUS	PD	TO	IDLEB	BOR		SKERR			000d .0..	uduu .d..	rw0,rw0,rw0,rw0 -,rw0,-,-
2DH	LVDCN1	ENLVD	LVD	VJ1	VJ2	VLDX[3:0]						
2EH	LVDCN2	VSL	SVIN[3:0]				SVIP[2:0]					
2FH	SBMSET1	SKRST		HAOTR[5:0]						x.xx xxxx	u.uu uuuu	*,-,*,*,*,*,*,*
30H	MCKCN1	HSSEL	CPUCK[1:0]		HSS[1:0]		HSCK	ENXT	ENHAO	0000 0001	0000 0001	*,*,*,*,*,*,*,*
31H	MCKCN2	LCDS[2:0]			ADCCK	PERCK	BZS[2:0]			0000 0000	0000 0000	*,*,*,*,*,*,*,*
32H	TMACN	ENTMA	TMACK	TMAS[1:0]		ENWDT	WDTS[2:0]			0000 0000	0000 0000	*,*,*,*,w1,*,*,*
33H	TMAR	TimerA data register								xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r
34H	TMCCN	ENTMC	TMCCK[1:0]		TMCS1[2:0]			TMCS0[1:0]		0000 0000	0000 0000	*,*,*,*,*,*,*,*
35H	PRC	TimerC programmable register								1111 1111	1111 1111	*,*,*,*,*,*,*,*
36H	TMCR	TimerC register								0000 0000	0000 0000	r,r,r,r r,r,r,r
37H	PWMCN	ENPWM		PWMRL[1:0]						0000 0000	0000 0000	*,*,*,*,*,*,*,*
38H	PWMR	PWM MSB Byte register								xxxx xxxx	uuuu uuuu	*,*,*,*,*,*,*,*
39H	LCDCN1	ENLCD	LCDPR	VLCDX[1:0]		LCDBF	LCDBI[1:0]			0000 000.	0000 000.	*,*,*,*,*,*,*,-
3AH	LCDCN2	LCDBL	LCDMX[1:0]							000.	000.	*,*,*,- -,-,-,-
3BH	LCD0	Segment SEG1@[7:4] and SEG0@[3:0] data register of LCD								xxxx xxxx	uuuu uuuu	*,*,*,*,*,*,*,*
3CH	LCD1	Segment SEG3@[7:4] and SEG2@[3:0] data register of LCD								xxxx xxxx	uuuu uuuu	*,*,*,*,*,*,*,*
3DH	LCD2	Segment SEG5@[7:4] and SEG4@[3:0] data register of LCD								xxxx xxxx	uuuu uuuu	*,*,*,*,*,*,*,*
3EH	LCD3	Segment SEG7@[7:4]and SEG6@[3:0] data register of LCD								xxxx xxxx	uuuu uuuu	*,*,*,*,*,*,*,*
3FH	LCD4	Segment SEG9@[7:4] and SEG8@[3:0] data register of LCD								xxxx xxxx	uuuu uuuu	*,*,*,*,*,*,*,*
40H	LCD5	Segment SEG11@[7:4] and SEG10@[3:0] data register of LCD								xxxx xxxx	uuuu uuuu	*,*,*,*,*,*,*,*
41H												
42H												
46H												
47H												
48H												
49H												
4AH												
4BH												
4CH												

Figure 4-2 HY12P62 Register List

"-"no use,"*"read/write,"w"write,"r"read,"r0"only read 0,"r1"only read 1,"w0"only write 0,"w1"omly write 1												
"."unimplemented bit,"x"unknown,"u"unchanged,"d"depends on condition												
Address	**File Name**	**Bit7**	**Bit6**	**Bit5**	**Bit4**	**Bit3**	**Bit2**	**Bit1**	**Bit0**	**A-RESET**	**i-RESET**	**R/W**
4DH	PT1	PT1.7				PT1.3	PT1.2	PT1.1	PT1.0	xxxx xxxx	uuuu uuuu	*,*,*,*,r,r,r,r
4EH	TRISC1	TC1.7					TC1.2	TC1.1	TC1.0	0000 0000	0000 0000	*,*,*,*,*,*,*,*
4FH	PT1PU	PU1.7				PU1.3	PU1.2	PU1.1	PU1.0	0000 0000	0000 0000	*,*,*,*,*,*,*,*
50H	PT1M1	PM1.7				INTEG1[1:0]		INTEG0[1:0]		0000 0000	0000 0000	*,*,*,*,*,*,*,*
51H	PT2	PT2.7	PT2.6	PT2.5	PT2.4	PT2.3	PT2.2	PT2.1	PT2.0	xxxx xxxx	uuuu uuuu	*,*,*,*,*,*,*,*
52H	TRISC2	TC2.7	TC2.6	TC2.5	TC2.4	TC2.3	TC2.2	TC2.1	TC2.0	0000 0000	0000 0000	*,*,*,*,*,*,*,*
53H	PT2DA	DA2.7	DA2.6	DA2.5	DA2.4	DA2.3		PM2.2[1:0]		0000 0.00	0000 0.00	*,*,*,*,-,*,*
54H	PT2PU	PU2.7	PU2.6	PU2.5	PU2.4	PU2.3	PU2.2	PU2.1	PU2.0	0000 0000	0000 0000	*,*,*,*,*,*,*,*
55H	PT3		PT3.6				TC3.6			xxx. 000.	uuu. 000.	*,*,*,-,*,*,*,-
56H	PT3PU		PU3.6							000. 0.0.	000. 0.0.	*,*,*,-,*,-,*,-
57H	PAX6					PS6	DS6	FS6	SS6	0000 0000	0000 0000	*,*,*,*,*,*,*,*
58H	PA54	PS5	DS5	FS5	SS5	PS4	DS4	FS4	SS4	0000 0000	0000 0000	*,*,*,*,*,*,*,*
59H	PA32	PS3	DS3	FS3	SS3	PS2	DS2	FS2	SS2	0000 0000	0000 0000	*,*,*,*,*,*,*,*
5AH	PA10	PS1	DS1	FS1	SS1	PS0	DS0	FS0	SS0	0000 0000	0000 0000	*,*,*,*,*,*,*,*
5BH	PWRCN	DMMBIAS	SAGND[1:0]		ENVS	ENREFO	ENLDO	LDOC[1:0]=11		0000 0000	0000 0000	*,*,*,*,*,*,*,*
5CH	PWRCN2	MCUBIAS		ENCMP	ENCNTI	ENCTR	RSTCOMB	RSLPF	RSRMS	0000 0000	0000 0000	*,*,*,*,*,*,*,*
5DH	ADCN1	SDIO	SREFO	SFT1<1:0>		SFUVR<3:0>				0000 0000	0000 0000	*,*,*,*,*,*,*,*
5EH	ADCN2	SMODE<7:0>								0000 0000	0000 0000	*,*,*,*,*,*,*,*
5FH	ADCN3	SCMPRH<3:0>				SCMPRL<3:0>				0000 0000	0000 0000	*,*,*,*,*,*,*,*
60H	ADCN4	SCMPI<2:0>			AD1CHOP<1:0>		AD1OSR<2:0>			0000 0000	0000 0000	*,*,*,*,*,*,*,*
61H	ADCN5	SAD1FP<3:0>				HSAD	SAD1FN<2:0>			0000 0000	0000 0000	*,*,*,*,*,*,*,*
62H	ADCN6	SAD1RH<2:0>			SAD1RL<2:0>			SAD1I<1:0>		0000 0000	0000 0000	*,*,*,*,*,*,*,*
63H	ADCN7	ENAD1	AD1IG<1:0>		AD1RG	AD1RHBUF	AD1RLBUF	AD1IPBUF	AD1INBUF	0000 0000	0000 0000	*,*,*,*,*,*,*,*
64H	RMSCN	ENRMS	ENLPF	ENSQRE=1	LPFBW<1>=1	LPFBW<0>				0000 0000	0000 0000	*,*,*,*,*,*,*,*
65H	CTAU	CTA<23:16>								xxxx xxxx	uuuu uuuu	*,*,*,*,*,*,*,*
66H	CTAH	CTA<15:8>								xxxx xxxx	uuuu uuuu	*,*,*,*,*,*,*,*
67H	CTAL	CTA<7:0>								xxxx xxxx	uuuu uuuu	*,*,*,*,*,*,*,*
68H	CTBU	CTB<23:16>								xxxx xxxx	uuuu uuuu	*,*,*,*,*,*,*,*
69H	CTBH	CTB<15:8>								xxxx xxxx	uuuu uuuu	*,*,*,*,*,*,*,*
6AH	CTBL	CTB<7:0>								xxxx xxxx	uuuu uuuu	*,*,*,*,*,*,*,*
6BH	CTCU	CTC<23:16>								xxxx xxxx	uuuu uuuu	*,*,*,*,*,*,*,*
6CH	CTCH	CTC<15:8>								xxxx xxxx	uuuu uuuu	*,*,*,*,*,*,*,*
6DH	CTCL	CTC<7:0>								xxxx xxxx	uuuu uuuu	*,*,*,*,*,*,*,*
6EH	CTSTA	CNTI	ACPO	CMPHO	CMPLO				CTBOV			
6FH												
70H												
71H												
72H												
73H												
74H												
75H	RMSDATA4	RMS<37:30>								xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r
76H	RMSDATA3	RMS<29:22>								xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r
77H	RMSDATA2	RMS<21:14>								xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r
78H	RMSDATA1	RMS<13:6>								xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r
79H	RMSDATA0	RMS<5:0>								xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r
7AH	LPFDATAU	LPF<18:11>								xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r
7BH	LPFDATAH	LPF<10:3>								xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r
7CH	LPFDATAL	LPF<2:0>								xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r
7DH	AD1DATAU	AD1<18:11>								xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r
7EH	AD1DATAH	AD1<10:3>								xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r
7FH	AD1DATAL	AD1<2:0>								xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r
80H ~ FFH	GPR0	General Purpose Register as 128Byte								xxxx xxxx	uuuu uuuu	*,*,*,*,*,*,*,*
100H~17FH	GPR1	General Purpose Register as 128Byte								xxxx xxxx	uuuu uuuu	*,*,*,*,*,*,*,*

Figure 4-3 HY12P62 Register List (continued)

5. Absolute Maximum Ratings

Absolute maximum ratings over operating free-air temperature (unless otherwise noted)

Voltage applied at VDD (VDDA) to VSS (VSSA) . . . . . −0.2 V to 4.0 V

Voltage applied to any pin . . . . . −0.2 V to V_{DD} + 0.3 V

Diode current at any device terminal . . . . . ±2 mA

Storage temperature, Tstg: (unprogrammed device) . . . . . −55℃ to 125℃

(programmed device) . . . . . −40℃ to 85℃

Total power dissipation 0.5w

Lead temperature (soldering, 10s) . . . . . 300℃

5.1. Recommended Operating Conditions

T_A = -40℃~85℃, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	unit
V_{DD}	Supply Voltage	All digital peripherals and CPU	2.2		3.6	V
		Analog peripherals	2.5		3.6	
V_{SS}	Supply Voltage		0		0	

5.2. Internal RC Oscillator

T_A = 25℃, V_{DD}=3.0V, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	unit
HAO	High Speed Oscillator frequency	ENHAO[0]=1		4		MHz
LPO	Low Power Oscillator frequency	V_{DD} supply voltage be enable LPO		32		KHz

5.3. Supply Current into VDD Excluding Peripherals Current

T_A = 25℃, V_{DD}=3.0V, OSC_LPO=32KHz, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	unit
I_{AM1}	Active mode 1	OSC_HAO = 4MHz, CPU_CK = 4MHz		0.36	0.55	mA
I_{AM2}	Active mode 2	OSC_HAO = 4MHz, CPU_CK = 2MHz		0.2	0.3	mA
I_{LP3}	Low Power 3	OSC_HAO = off, CPU_CK = off, Sleep state		0.65	1.2	uA

OSC_HAO：Internal High Accuracy Oscillator frequency.

CPU_CK：CPU core work frequency.

5.4. Port 1~2

T_A = 25℃, V_{DD}=3.0V, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	unit
Input voltage and Schmitt trigger and leakage current and timing						
V_{IH}	High-Level input voltage				2.1	V
V_{IL}	Low-Level input voltage		0.9			
V_{hys}	Input Voltage hysteresis(VIH - VIL)			0.8		V
I_{LKG}	Leakage Current				0.1	uA
R_{PU}	Port pull high resistance			180		kΩ
Output voltage and current and frequency						
V_{OH}	High-level output voltage	I_{OH}=10mA	V_{DD} -0.3			V
V_{OL}	Low-level output voltage	I_{OL}=-10mA			VSS +0.3	

5.5. Reset(Brownout, External RST pin, Low Voltage Detect)

T_A = 25℃, V_{DD}=3.0V, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	unit
BOR	Pulse length needed to accepted reset internally, t_{d-LVR}		2			us
	V_{DD} Start Voltage to accepted reset internally (L➔H),V_{LVR}		1.6	1.85	2.1	V
	Hysteresis, $V_{HYS-LVR}$			70		mV
RST	Pulse length needed as RST/VPP pin to accepted reset internally, t_{d-RST}		2			us
	Input Voltage to accepted reset internally		0.9			V
	Hysteresis, $V_{HYS-RST}$			0.8		V
LVD Compare Mode	Operation current, I_{LVD}			10	15	uA
	External input voltage to compare reference voltage			1.2		V
	Compare reference voltage temperature drift	T_A = -40℃ ~ 85 ℃		100		ppm/℃
	Detect V_{DD} voltage rang by user option, V_{SVS} VLDx[3:0]=1110b			3.3		V
	Detect V_{DD} voltage rang by user option, V_{SVS} VLDx[3:0]=1101b			3.2		
	Detect V_{DD} voltage rang by user option, V_{SVS} VLDx[3:0]=1100b			3.1		
	Detect V_{DD} voltage rang by user option, V_{SVS} VLDx[3:0]=1011b			3.0		
	Detect V_{DD} voltage rang by user option, V_{SVS} VLDx[3:0]=1010b			2.9		
	Detect V_{DD} voltage rang by user option, V_{SVS} VLDx[3:0]=1001b			2.8		
	Detect V_{DD} voltage rang by user option, V_{SVS} VLDx[3:0]=1000b			2.7		
	Detect V_{DD} voltage rang by user option, V_{SVS} VLDx[3:0]=0111b			2.6		
	Detect V_{DD} voltage rang by user option, V_{SVS} VLDx[3:0]=0110b			2.5		
	Detect V_{DD} voltage rang by user option, V_{SVS} VLDx[3:0]=0101b			2.4		
	Detect V_{DD} voltage rang by user option, V_{SVS} VLDx[3:0]=0100b			2.3		
	Detect V_{DD} voltage rang by user option, V_{SVS} VLDx[3:0]=0011b			2.2		
	Detect V_{DD} voltage rang by user option, V_{SVS} VLDx[3:0]=0010b			2.1		
	Detect V_{DD} voltage rang by user option, V_{SVS} VLDx[3:0]=0001b			2.0		
VDD Ratio Compare Mode	Comparator Offset Error		-150		150	mV
	VDD Ratio Error		-5		5	%

BOR：Brownout Reset

LVR：Low Voltage Reset of BOR

LVD：Low Voltage Detect

RST：External Reset pin

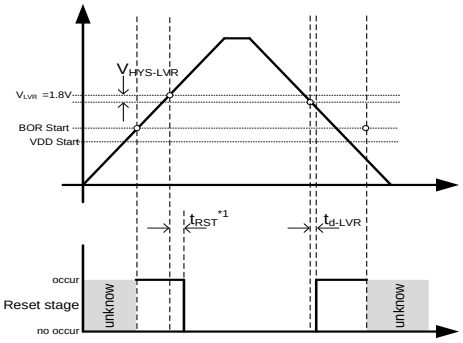


Figure6.5-1 BOR reset diagram

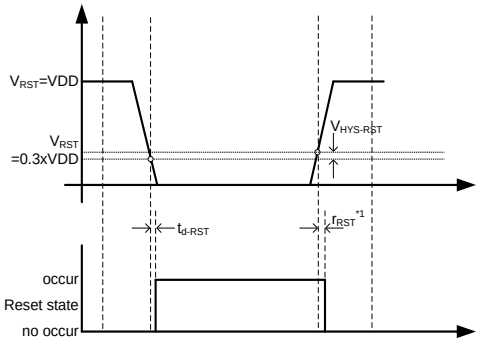


Figure6.5-2 RST reset diagram

*1 r_{RST}：Please see BOR Introduce of HY12Pxx series User's Guide (UG-HY12S65-Vxx).

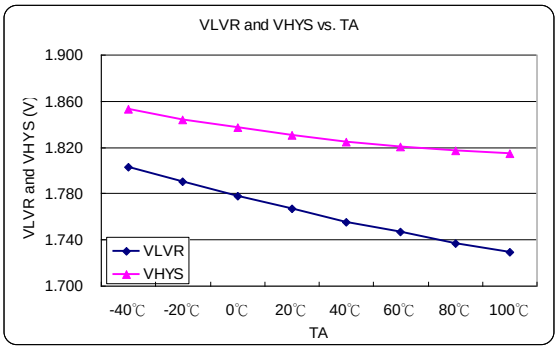


Figure6.5-3 VLVR and VHYS vs. Temperature

5.6. Power System

T_A = 25℃, V_{DD}=3.0V, unless otherwise noted

Sym.	Parameter	Test Conditions		Min.	Typ.	Max.	unit
VDDA	VDDA operation current, I_{VDDA}	I_L = 0mA	LDOC[1:0]=11b		22		uA
	Select VDDA output voltage	I_L = 0.1mA, VDD=3V	LDOC[1:0]=11b		3.6		V
	Load Regulaion	VDD=2.5V I_L = 1~5mA	LDOC[1:0]=11b		10		mV
	Line Regulation	VDD=2.5V~3.6V I_L = 1mA	LDOC[1:0]=11b		40		mV
	Temperature drift	LDOC[1:0]=11b	T_A=-40℃~85℃		100		ppm/℃
	V_{DD} Voltage drift	I_L = 0.1mA	V_{DD}=2.5V~3.6V		±0.2		%/V
AGND	AGND operation current, I_{Agnd}	SAGND≠00b	I_L = 0mA		20		uA
	Output voltage ,V_{Agnd}		I_L = 0uA		1.0		V
	Output voltage with Load		I_L = ±200uA	0.98		1.02	V_{AGND}
REFO	V(REFO,AGND)	ENLDO=1b, SAGND≠00b	I_L = 0uA		1,2		V
	Temperature drift		T_A=-40℃~85℃		100		ppm/℃
	RMS Noise				60		uVrms

5.7. LCD

T_A = 25℃, V_{DD}=3.0V, C_{VLCD} =4.7uF, unless otherwise noted.

Sym.	Parameter	Test Conditions		Min.	Typ.	Max.	unit
I_{LCD}	Operation supply current without output buffer.(all segment turn on)	LCDPR[0]=1	V_{DD} = 2.2V		20		uA
			V_{DD} = 3.0V				
VLCD	Supply Voltage at VLCD pin	LCDPR[0]=0		2.2		3.6	V
	Embedded Charge Pump output voltage at VLCD pin	V_{DD} = 2.2V, LCDPR[0]=1, C_{VLCD} =4.7uF	VLCDX[1:0]=11b	2.295	2.55	2.805	V
			VLCDX[1:0]=10b	2.52	2.8	3.08	
			VLCDX[1:0]=01b	2.745	3.05	3.355	
			VLCDX[1:0]=00b	2.97	3.3	3.63	
Z_{LCD}	Output impedance with LCD buffer	f_{LCD} =128Hz,VLCD=3.05V			10		kΩ

5.8. ΣΔADC, Power Supply and Recommended Operating Conditions

T_A = 25℃, V_{DD}=3.0V, VDDA=2.4V, VR=1.2V, AGND=0.3VDDA, ADC Clock=400kHz Input buffer on unless otherwise noted

Sym.	Parameter	Test Conditions		Min.	Typ.	Max.	unit
$f_{\Sigma\Delta ADC}$	Modulator sample frequency, ADC_CK				400		KHz
$I_{\Sigma\Delta ADC}$	Operation supply current	Input gain =0.9, input buffer on ADC_CK=400KHz			550		uA
$D_{\Sigma\Delta ADC}$	Maximum ADC Output Code (ADC Gain Factor)	OSR=2500~20000			17D79		d
		OSR=64~256			3FFFF		
		OSR=32			3FD7C		
Eos	Input offset voltage	Chopper on OSR=20000	Input gain=0.9, reference gain=1		20	100	uV
			Input gain=3.6, reference gain=0.33		5	10	
Rev	Roll-over error voltage	Chopper on OSR=20000	Input gain=0.9, reference gain=1		200	600	uV
			Input gain=3.6, reference gain=0.33		10	30	
Vrms	Input RMS Noise	Chopper on, OSR=20000, input gain=0.9 reference gain=1			10		uV
		Chopper on, OSR=20000, input gain=3.6 reference gain=0.33			2		
		Chopper off, OSR=32, input gain=0.9 reference gain=1			400		
		Chopper off, OSR=32, input gain=3.6 reference gain=0.33			80		
NM	Normal Rejection ratio	Chopper On OSR=20000 ADCLK=1	Input gain=0.9, reference gain=1. Vin=200mVrms 50/60Hz		60		dB
			Input gain=3.6, reference gain=0.33. Vin=20mVrms 50/60Hz				
AC_{bw}	AC Measurement Bandwidth (Sine wave only)	OSR=32, LPFBW=1024	0.5% error	20		350	Hz
			3dB		TBD		

5.9. ΣΔADC, Temperature Sensor

T_A=25, V_{DD}=3.0V, VDDA=2.4V, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	unit
TC_S	Sensor temperature drift			65		uV/℃
KT	Absolute Temperature Scale 0°K	ADC Gain=0.9, OSR=20000, Input buffer Off, VR:REFO-AGND AGND=0.3VDDA		-277		℃
TC_{ERR}	One point calibrate error temperature	Calibration at 25℃ of -40℃~85℃		±2		℃

5.10. Analog Input and Switch Performance

T_A=25℃, V_{DD}=3.0V, VDDA=2.4V, AGND=0.3VDDA, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	unit
I_{AL}	Analog Input Leakage Current	AGND=0.3VDDA		10	100	pA
		AGND=0.1VDDA		100	500	
Rsw	Switch Turn On Resistance	PS0,PS1		20		Ohm
		DS0,DS1		40		
		DS2~DS5, PS2~PS5		80		
		SS0~SS5,FS0~FS5		400		

5.11. DMM Comparator

T_A=25℃, V_{DD}=3.0V, VDDA=2.4V, AGND=0.3VDDA, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	unit
I_{CMP}	Comparator Supply Current					uA
V_I	Comparator Input Range	CMPL	0		VDDA-0.7	V
		CMPH	0.4		VDDA	
Vos	Comparator Input Offset Voltage	CMPL , VRLCMP=AGND		5		mV
		CMPH , VRHCMP=AGND		5		
Vn	Comparator Input peak to peak noise	CMPL		5		mV
		CMPH		5		
		CMPH&CMPL		10		
CMP_{BW}	Comparator Bandwidth	VRHCMP=AGNDP<2>, VRLCMP=AGNDN<2> VIN=100mVrms		1		MHz

5.12. Built-in EPROM (BIE)

T_A=25℃, V_{DD}=3.0V, VDDA=2.4V, AGND=0.3VDDA, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	unit
V_{BIE}	Supply Voltage			6.0	6.5	V
$_{BIE}$	Operation supply current			5		mA
V_{SS}	Supply Voltage			0		V

6. Ordering Information

Device No.[1]	Package Type	Pins	Package Drawing		Code[2]	Shipment Packing Type	Unit Q'ty	Material Composition	MSL[3]
HY12P62-D000	Die	-	D	000	000	-	100	Green4	-
HY12P62-L064	LQFP	64	L	064	000	Tray	250	Green[4]	MSL-3

[1] **Device No.: Model No. – Package Type Description – Code** (Blank Code/ Standard/ Customized Programming Code)

Ex: Your customized programming code is 008 and you require die shipment.
The device No. will be HY12P62-D000-008.

Ex: You request blank code in die package.
The device No. will be HY12P62-D000.

Ex: You request blank code in LQFP 64 package.
The device No. will be HY12P62-L064.
And please clearly indicate the shipment packing type when placing orders.

Ex: Your customized programming code is 008 and you require products in LQFP 64 package.
The device No. will be HY12P62-L064-008.
And please clearly indicate the shipment packing type when placing orders.

[2] **Code :**

"001"~ "999" is standard or customized programming code.
Blank code does not have these numbers.

[3] **MSL:**

The Moisture Sensitivity Level ranking conforms to IPC/JEDEC J-STD-020 industry standard categorization.
The products are processed, packed, transported and used with reference to IPC/JEDEC J-STD-033.

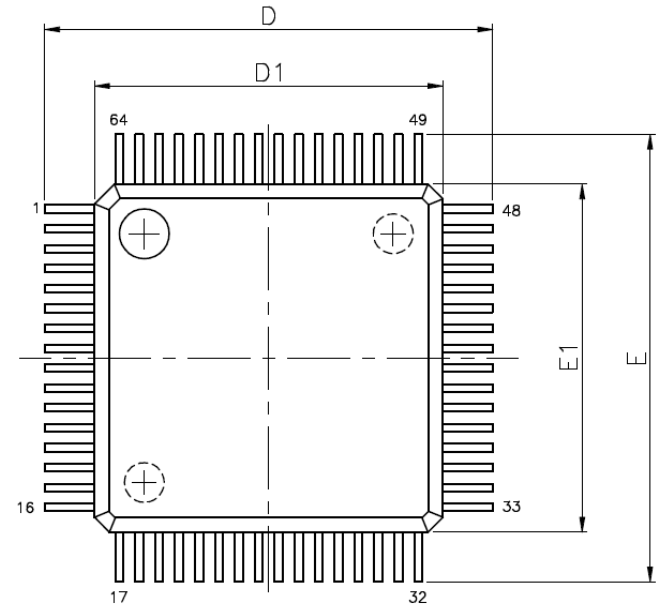
[4] **Green (RoHS & no Cl/Br):**

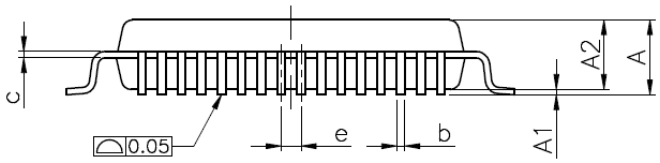
HYCON products are Green products that are compliant with RoHS directive, SVHC under REACH and Halogen free.

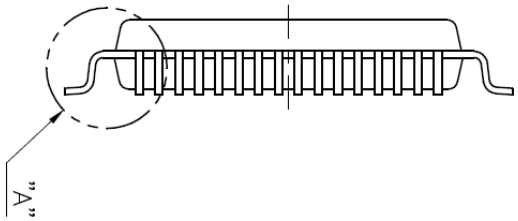
7. Packaging Information

7.1. LQFP64(L064)

7.1.1. Package Dimensions

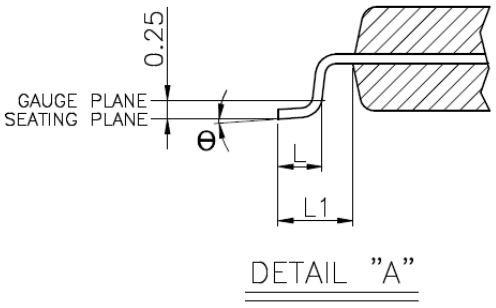






VARIATIONS (ALL DIMENSIONS SHOWN IN MM)

SYMBOLS	MIN.	NOM.	MAX.
A	—	—	1.60
A1	0.05	—	0.15
A2	1.35	1.40	1.45
b	0.13	0.18	0.23
c	0.09	—	0.20
D		9.00 BSC	
D1		7.00 BSC	
e		0.40 BSC	
E		9.00 BSC	
E1		7.00 BSC	
L	0.45	0.60	0.75
L1		1.00 REF	
θ	0°	3.5°	7°



Note:

1. All dimensions refer to JEDEC OUTLINE MS-026.
2. Do not include Mold Flash or Protrusions.
3. Unit: mm

8. Revision Record

Major differences are stated thereinafter.

Version	Page	Date	Revision Summary
V01	All	2014/09/16	First edition
V02	All	2014/10/28	Document revised
V03	5	2017/09/15	Add Function List
	14		Update Package marker information
	25		Update Green (RoHS & no Cl/Br)
V04	10~13	2018/08/15	Update Package LQFP64(L064) information